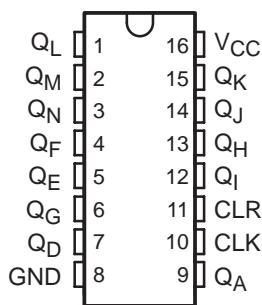
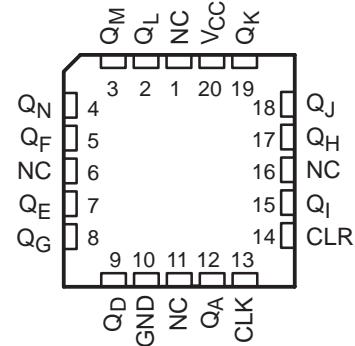


- Wide Operating Voltage Range of 2 V to 6 V
- Outputs Can Drive Up To 10 LSTTL Loads
- Low Power Consumption, 80- μ A Max I_{CC}
- Typical $t_{pd} = 12$ ns
- ± 4 -mA Output Drive at 5 V
- Low Input Current of 1 μ A Max

SN54HC4020 . . . J OR W PACKAGE
SN74HC4020 . . . D, DB, N, NS, OR PW PACKAGE
(TOP VIEW)



SN54HC4020 . . . FK PACKAGE
(TOP VIEW)



NC – No internal connection

description/ordering information

The 'HC4020 devices are 14-stage binary ripple-carry counters that advance on the negative-going edge of the clock pulse. The counters are reset to zero (all outputs low) independently of the clock (CLK) input when the clear (CLR) input goes high.

ORDERING INFORMATION

T _A	PACKAGE [†]		ORDERABLE PART NUMBER	TOP-SIDE MARKING
–40°C to 85°C	PDIP – N	Tube of 25	SN74HC4020N	SN74HC4020N
		Tube of 40	SN74HC4020D	HC4020
		Reel of 2500	SN74HC4020DR	
		Reel of 250	SN74HC4020DT	
	SOIC – D	Reel of 2000	SN74HC4020NSR	HC4020
	SOP – NS	Reel of 2000	SN74HC4020DBR	HC4020
		Tube of 90	SN74HC4020PW	HC4020
		Reel of 2000	SN74HC4020PWR	
	TSSOP – PW	Reel of 250	SN74HC4020PWT	
–55°C to 125°C	TSSOP – PW	CDIP – J	SNJ54HC4020J	SNJ54HC4020J
		CFP – W	SNJ54HC4020W	SNJ54HC4020W
		LCCC – FK	SNJ54HC4020FK	SNJ54HC4020FK

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



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On products compliant to MIL-PRF-38535, all parameters are tested unless otherwise noted. On all other products, production processing does not necessarily include testing of all parameters.

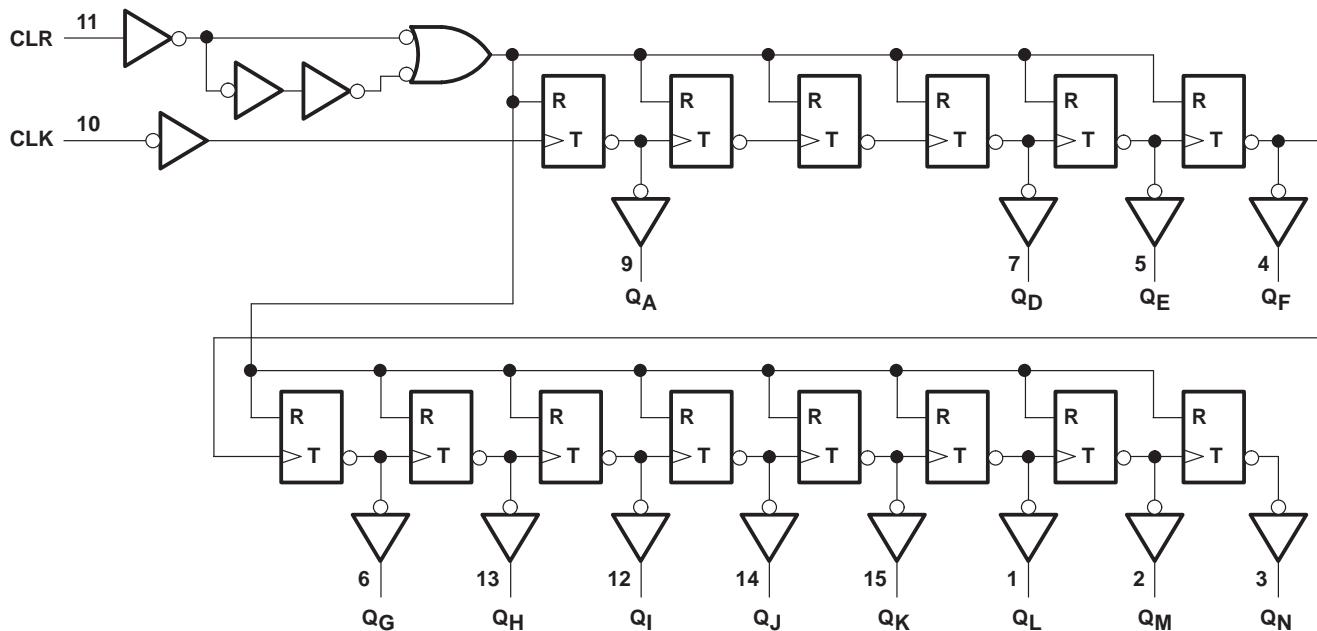
SN54HC4020, SN74HC4020 14-BIT ASYNCHRONOUS BINARY COUNTERS

SCLS158E – DECEMBER 1982 – REVISED SEPTEMBER 2003

FUNCTION TABLE (each buffer)

INPUTS		FUNCTION
CLK	CLR	
↑	L	No change
↓	L	Advance to next stage
X	H	All outputs L

logic diagram (positive logic)



Pin numbers shown are for the D, DB, J, N, NS, PW, and W packages.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Functional operation is limited by absolute maximum ratings to ensure reliability. Operation beyond absolute maximum ratings may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed. 2. The device will become hot during high current operation. Use JEDEC 51-7.

SN54HC4020, SN74HC4020
14-BIT ASYNCHRONOUS BINARY COUNTERS

SCLS158E – DECEMBER 1982 – REVISED SEPTEMBER 2003

recommended operating conditions (see Note 3)

			SN54HC4020			SN74HC4020			UNIT
			MIN	NOM	MAX	MIN	NOM	MAX	
V _{CC}	Supply voltage		2	5	6	2	5	6	V
V _{IH}	High-level input voltage	V _{CC} = 2 V		1.5		1.5		1.5	V
		V _{CC} = 4.5 V		3.15		3.15		3.15	
		V _{CC} = 6 V		4.2		4.2		4.2	
V _{IL}	Low-level input voltage	V _{CC} = 2 V			0.5			0.5	V
		V _{CC} = 4.5 V			1.35			1.35	
		V _{CC} = 6 V			1.8			1.8	
V _I	Input voltage		0	V _{CC}		0	V _{CC}		V
V _O	Output voltage		0	V _{CC}		0	V _{CC}		V
Δt/Δv	Input transition rise/fall time	V _{CC} = 2 V			1000			1000	ns
		V _{CC} = 4.5 V			500			500	
		V _{CC} = 6 V			400			400	
T _A	Operating free-air temperature		-55		125	-40		85	°C

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V _{CC}	T _A = 25°C			SN54HC4020		SN74HC4020		UNIT	
			MIN	TYP	MAX	MIN	MAX	MIN	MAX		
V _{OH}	V _I = V _{IH} or V _{IL}	I _{OH} = -20 μA	2 V	1.9	1.998	1.9		1.9		V	
			4.5 V	4.4	4.499	4.4		4.4			
			6 V	5.9	5.999	5.9		5.9			
		I _{OH} = -4 mA	4.5 V	3.98	4.3	3.7		3.84			
			6 V	5.48	5.8	5.2		5.34			
		I _{OL} = 20 μA	2 V		0.002	0.1	0.1		0.1		
V _{OL}	V _I = V _{IH} or V _{IL}		4.5 V		0.001	0.1	0.1		0.1		
			6 V		0.001	0.1	0.1		0.1		
			I _{OL} = 4 mA	4.5 V		0.17	0.26	0.4	0.33		
			I _{OL} = 5.2 mA	6 V		0.15	0.26	0.4	0.33		
I _I	V _I = V _{CC} or 0	6 V		±0.1	±100		±1000		±1000	nA	
I _{CC}	V _I = V _{CC} or 0, I _O = 0	6 V			8	160		80	μA		
C _i		2 V to 6 V		3	10		10		10	pF	

SN54HC4020, SN74HC4020 14-BIT ASYNCHRONOUS BINARY COUNTERS

SCLS158E – DECEMBER 1982 – REVISED SEPTEMBER 2003

timing requirements over recommended operating free-air temperature range (unless otherwise noted)

			V _{CC}	T _A = 25°C		SN54HC4020		SN74HC4020		UNIT
				MIN	MAX	MIN	MAX	MIN	MAX	
f _{clock}	Clock frequency			2 V	5.5	3.7	4.3			MHz
	4.5 V		28	19	22					
	6 V		33	22	25					
t _W	Pulse duration	CLK high or low	2 V	90		135		115		ns
			4.5 V	18		27		23		
			6 V	15		23		20		
		CLR high	2 V	70		105		90		
			4.5 V	14		21		18		
			6 V	12		18		25		
t _{SU}	Setup time, CLR inactive before CLK↓	2 V	60		90		75			ns
		4.5 V	12		18		15			
		6 V	10		15		13			

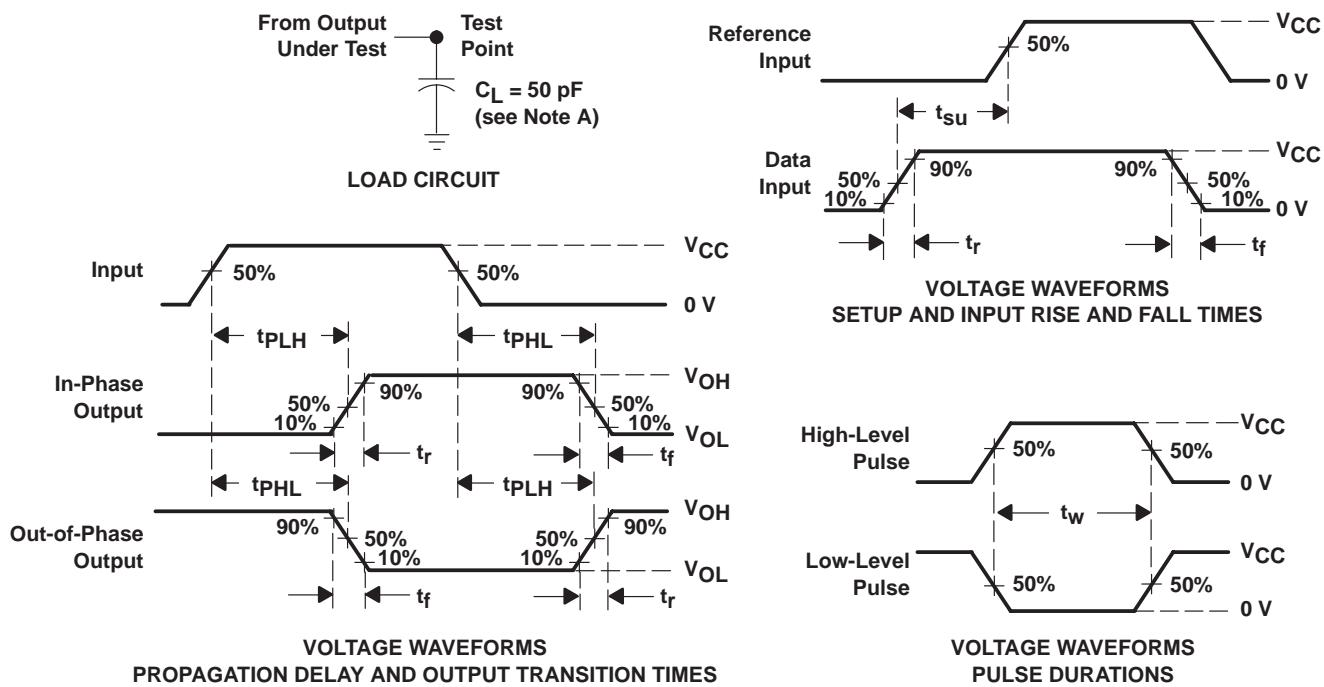
switching characteristics over recommended operating free-air temperature range, C_L = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC}	T _A = 25°C			SN54HC4020		SN74HC4020		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
f _{max}			2 V	5.5	10		3.7		4.3		MHz
			4.5 V	28	45		19		22		
			6 V	33	53		22		25		
t _{pd}	CLK	QA	2 V		62	150		225		190	ns
			4.5 V		16	30		45		38	
			6 V		12	26		38		32	
t _{PHL}	CLR	Any	2 V		63	140		210		175	ns
			4.5 V		17	28		42		35	
			6 V		13	24		36		30	
t _t		Any	2 V		28	75		110		95	ns
			4.5 V		8	15		22		19	
			6 V		6	13		19		16	

operating characteristics, T_A = 25°C

PARAMETER	TEST CONDITIONS	TYP	UNIT
C _{pd} Power dissipation capacitance	No load	88	pF

PARAMETER MEASUREMENT INFORMATION



NOTES:

- C_L includes probe and test-fixture capacitance.
- Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics: PRR $\leq 1 \text{ MHz}$, $Z_O = 50 \Omega$, $t_r = 6 \text{ ns}$, $t_f = 6 \text{ ns}$.
- For clock inputs, f_{max} is measured when the input duty cycle is 50%.
- The outputs are measured one at a time with one input transition per measurement.
- t_{PLH} and t_{PHL} are the same as t_{pd} .

Figure 1. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
85003012A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
8500301EA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type
8500301FA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type
SN54HC4020J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type
SN74HC4020D	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC4020DBR	ACTIVE	SSOP	DB	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC4020DBRE4	ACTIVE	SSOP	DB	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC4020DBRG4	ACTIVE	SSOP	DB	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC4020DE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC4020DG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC4020DR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC4020DRE4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC4020DRG4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC4020DT	ACTIVE	SOIC	D	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC4020DTE4	ACTIVE	SOIC	D	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC4020DTG4	ACTIVE	SOIC	D	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC4020N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74HC4020N3	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI
SN74HC4020NE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74HC4020NSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC4020NSRE4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC4020NSRG4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC4020PW	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC4020PWE4	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC4020PWG4	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC4020PWR	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC4020PWRE4	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN74HC4020PWRG4	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC4020PWT	ACTIVE	TSSOP	PW	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC4020PWTE4	ACTIVE	TSSOP	PW	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC4020PWTG4	ACTIVE	TSSOP	PW	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SNJ54HC4020FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54HC4020J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type
SNJ54HC4020W	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

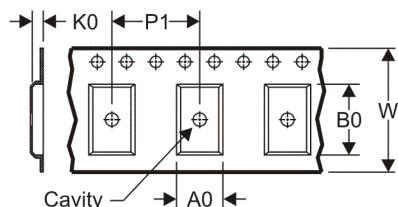
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

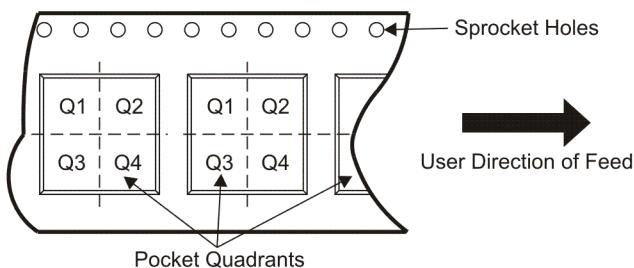
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TAPE AND REEL INFORMATION
REEL DIMENSIONS

TAPE DIMENSIONS


A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74HC4020DBR	SSOP	DB	16	2000	330.0	16.4	8.2	6.6	2.5	12.0	16.0	Q1
SN74HC4020DR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
SN74HC4020NSR	SO	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
SN74HC4020PWR	TSSOP	PW	16	2000	330.0	12.4	7.0	5.6	1.6	8.0	12.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74HC4020DBR	SSOP	DB	16	2000	346.0	346.0	33.0
SN74HC4020DR	SOIC	D	16	2500	333.2	345.9	28.6
SN74HC4020NSR	SO	NS	16	2000	346.0	346.0	33.0
SN74HC4020PWR	TSSOP	PW	16	2000	346.0	346.0	29.0

DB (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



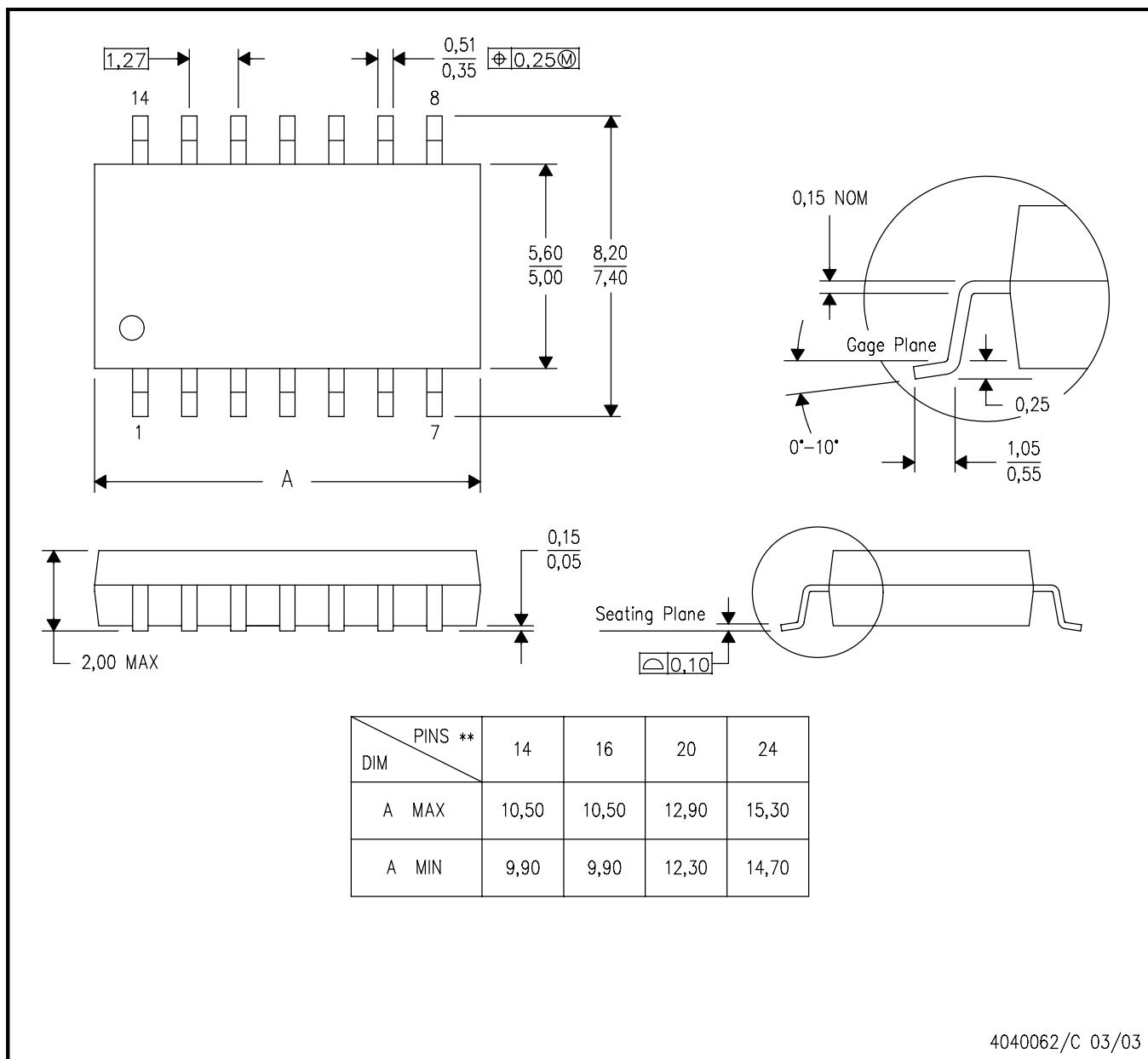
NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
 D. Falls within JEDEC MO-150

MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



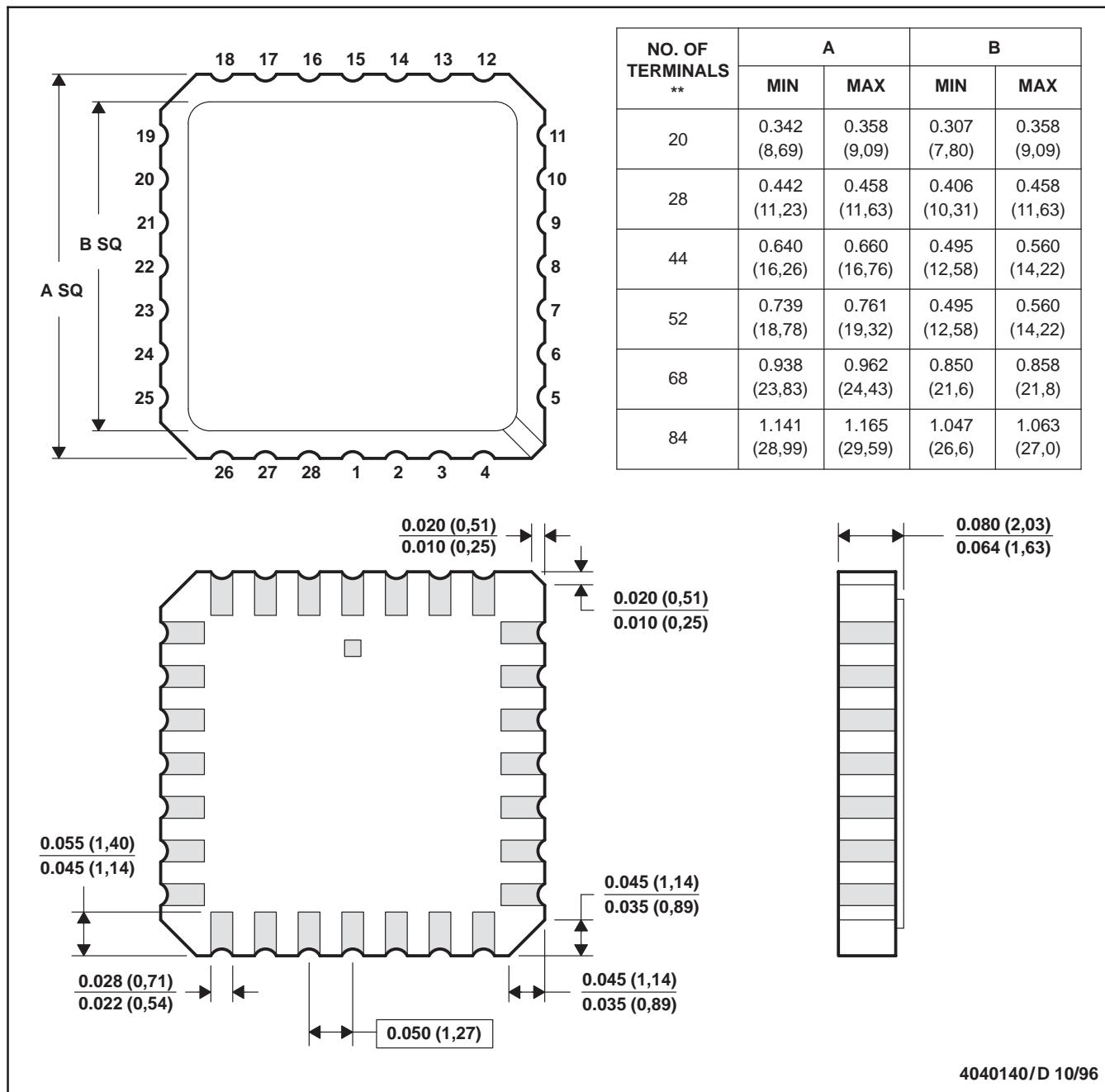
4040062/C 03/03

NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

FK (S-CQCC-N**)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. The terminals are gold plated.
- E. Falls within JEDEC MS-004

J (R-GDIP-T**)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



PINS ** DIM	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



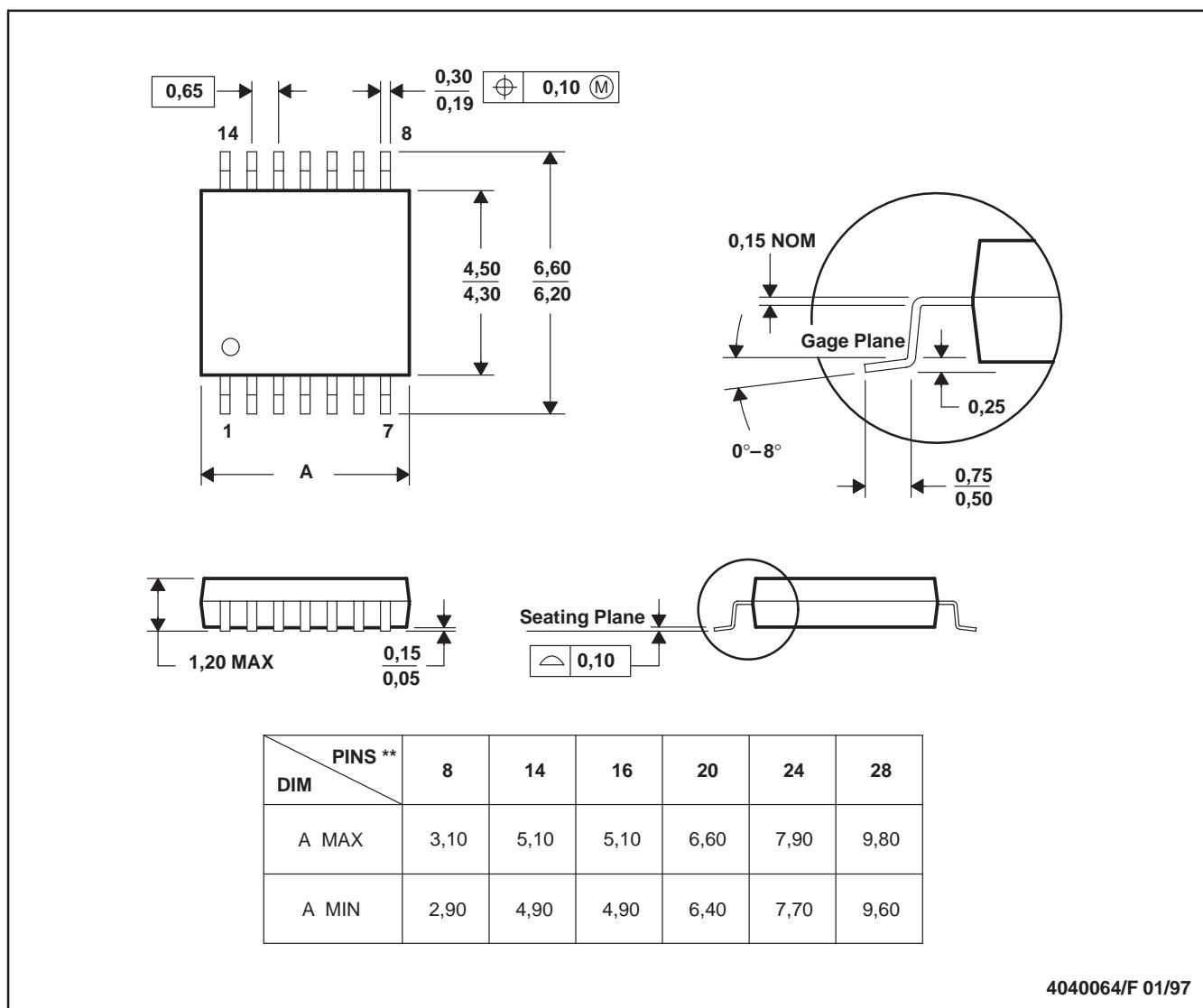
4040083/F 03/03

NOTES: A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. This package is hermetically sealed with a ceramic lid using glass frit.
D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

PW (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14 PINS SHOWN

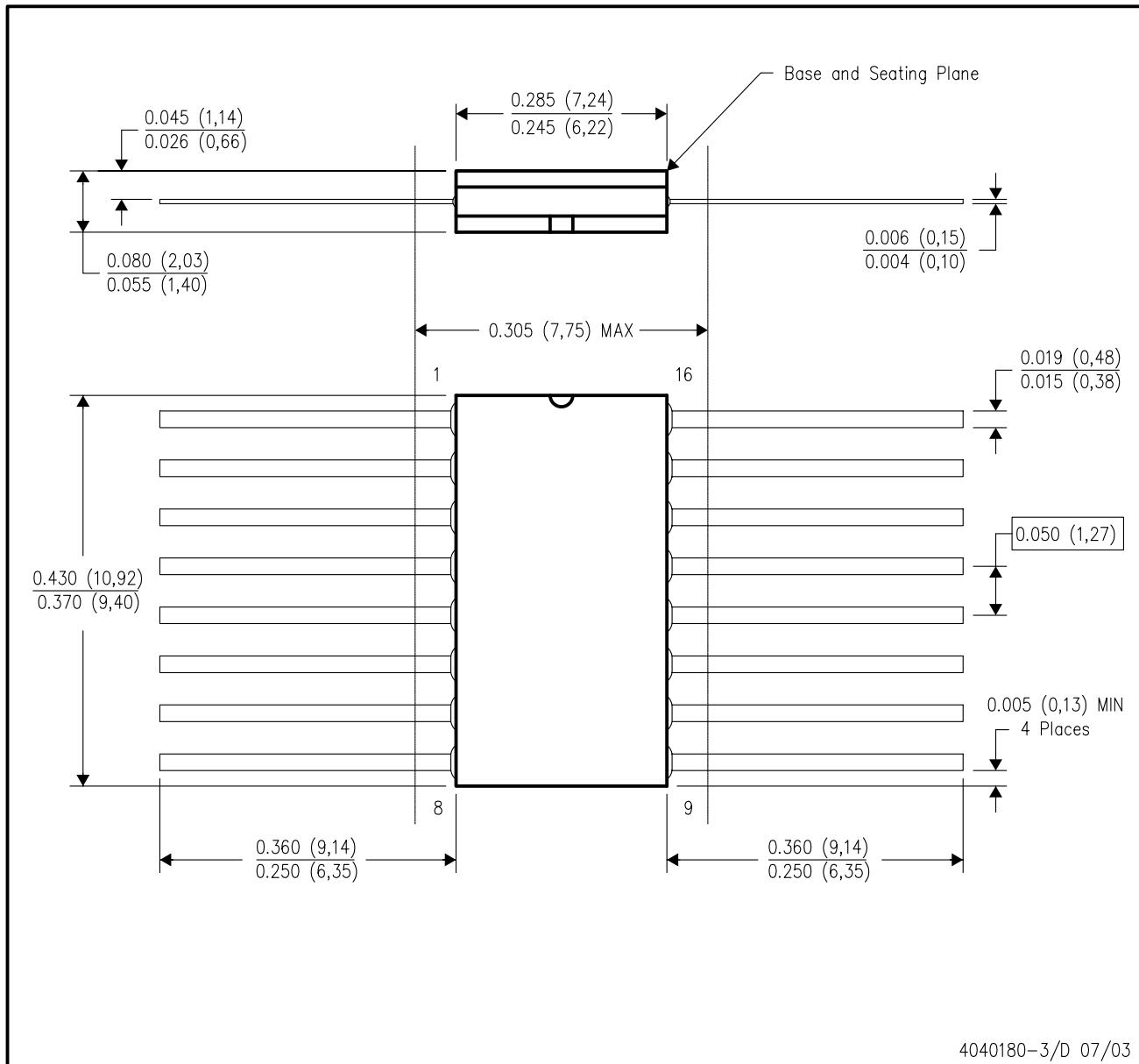


NOTES:

- All linear dimensions are in millimeters.
- This drawing is subject to change without notice.
- Body dimensions do not include mold flash or protrusion not to exceed 0,15.
- Falls within JEDEC MO-153

W (R-GDFP-F16)

CERAMIC DUAL FLATPACK

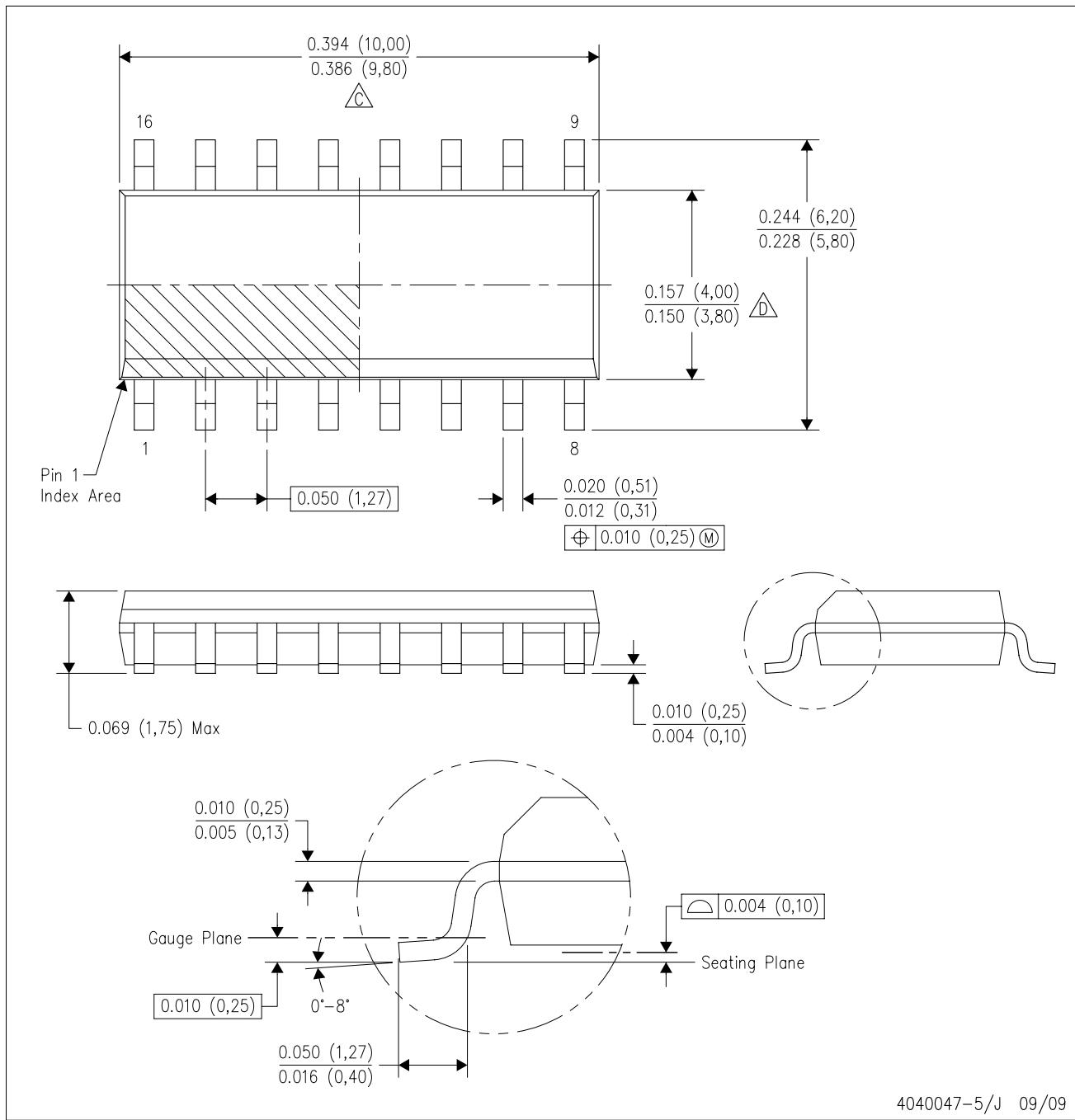


NOTES:

- All linear dimensions are in inches (millimeters).
- This drawing is subject to change without notice.
- This package can be hermetically sealed with a ceramic lid using glass frit.
- Index point is provided on cap for terminal identification only.
- Falls within MIL-STD 1835 GDFP1-F16 and JEDEC MO-092AC

D (R-PDSO-G16)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

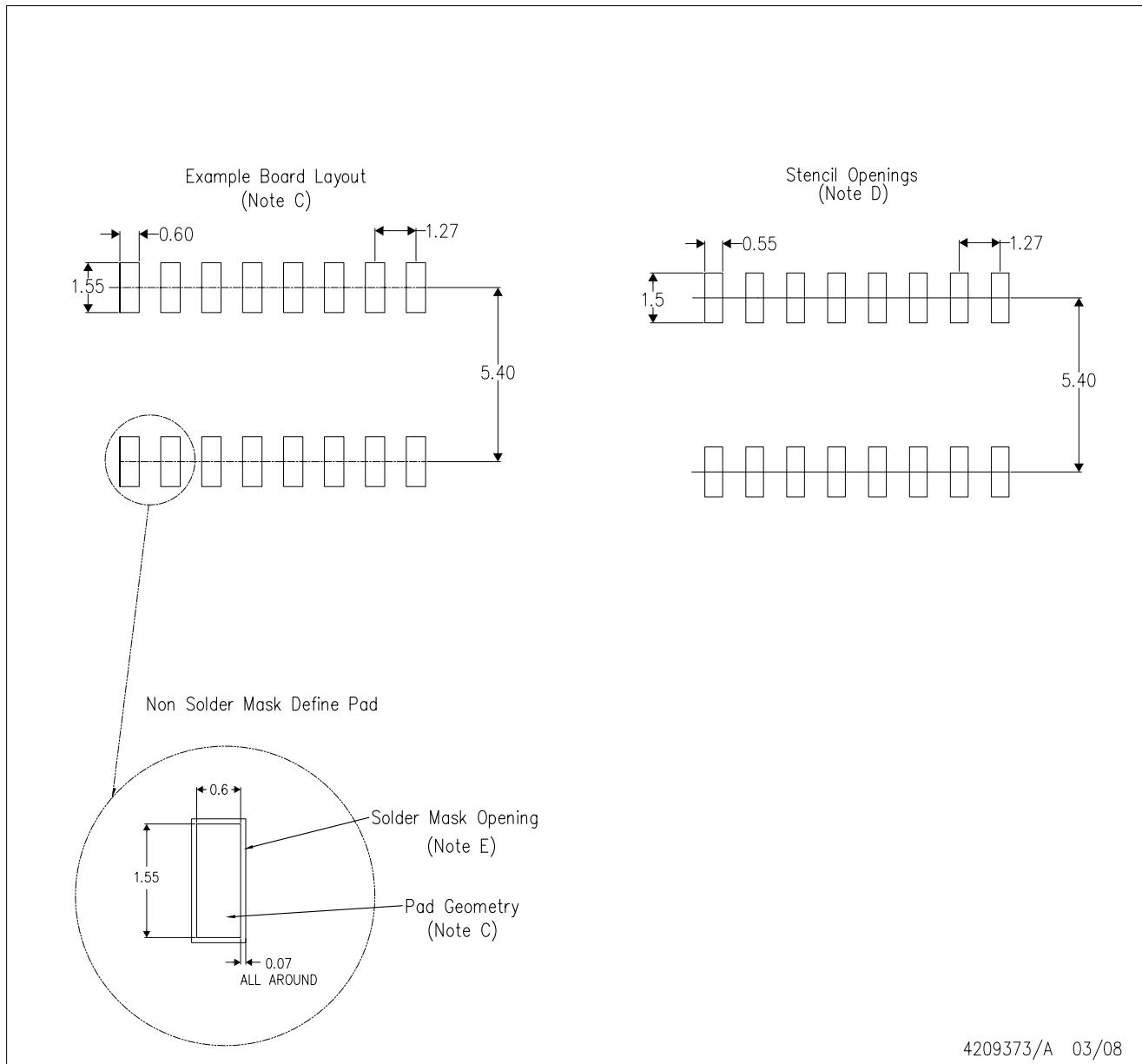
B. This drawing is subject to change without notice.

△C Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.

△D Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.

E. Reference JEDEC MS-012 variation AC.

D(R-PDSO-G16)



NOTES:

- All linear dimensions are in millimeters.
- This drawing is subject to change without notice.
- Refer to IPC7351 for alternate board design.
- Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525
- Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

N (R-PDIP-T**)

16 PINS SHOWN

PLASTIC DUAL-IN-LINE PACKAGE



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